ABSTRACT

A SYSTEM AND PROCESS FOR DICING INTEGRATED CIRCUITS

An assembly for cutting a plurality of substrates into individual integrated circuit units comprising a first block for receiving a first substrate, said first block movable between a first loading position, a first alignment inspection station and a first cutting zone; a second block for receiving a second substrate, said second block movable between a second loading position, a second alignment inspection station and a second cutting zone; a cutting device for cutting a substrate into individual integrated circuit units, said cutting device movable between the first cutting zone and the second cutting zone, and; an alignment inspection device for determining the alignment of a substrate positioned on either the first or second block, said alignment inspection device movable between the first alignment inspection station and the second alignment inspection station.

Figure 1

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